

74LVC74A

Dual D-type flip-flop with set and reset; positive-edge trigger

Rev. 06 — 4 June 2007

Product data sheet

1. General description

The 74LVC74A is a dual edge triggered D-type flip-flop with individual data (D) inputs, clock (CP) inputs, set (\overline{SD}) and (\overline{RD}) inputs, and complementary Q and \overline{Q} outputs.

The set and reset are asynchronous active LOW inputs and operate independently of the clock input. Information on the data input is transferred to the Q output on the LOW-to-HIGH transition of the clock pulse. The D inputs must be stable one set-up time prior to the LOW-to-HIGH clock transition, for predictable operation.

Schmitt trigger action at all inputs makes the circuit highly tolerant of slower input rise and fall times.

2. Features

- 5 V tolerant inputs for interlacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard JESD8-B/JESD36
- ESD protection:
 - ◆ HBM JESD22-A114D exceeds 2000 V
 - ◆ CDM JESD22-C101C exceeds 1000 V
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and $-40\text{ }^{\circ}\text{C}$ to $125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVC74AD	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74LVC74ADB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74LVC74APW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74LVC74ABQ	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85\text{ mm}$	SOT762-1

4. Functional diagram

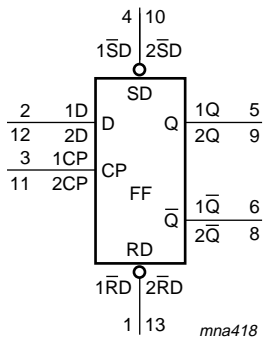


Fig 1. Logic symbol

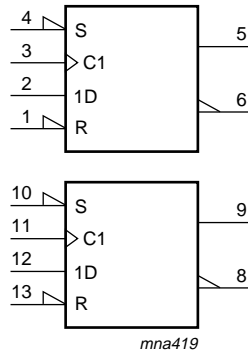


Fig 2. IEC logic symbol

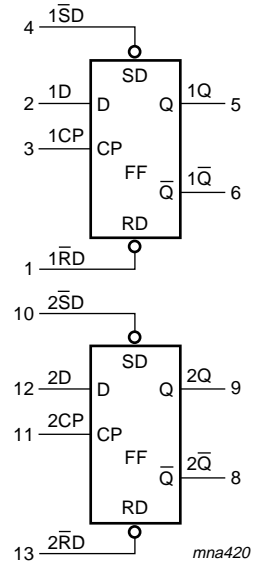


Fig 3. Functional diagram

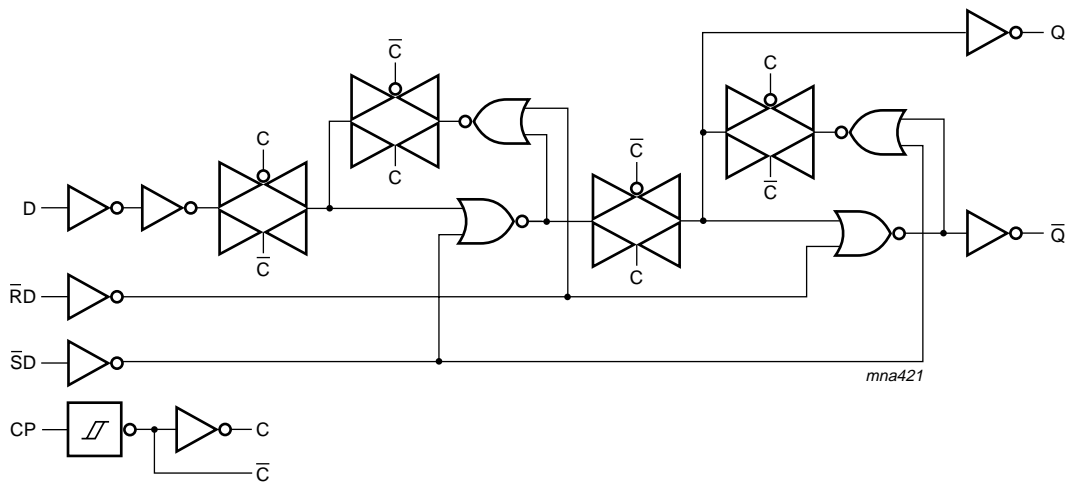
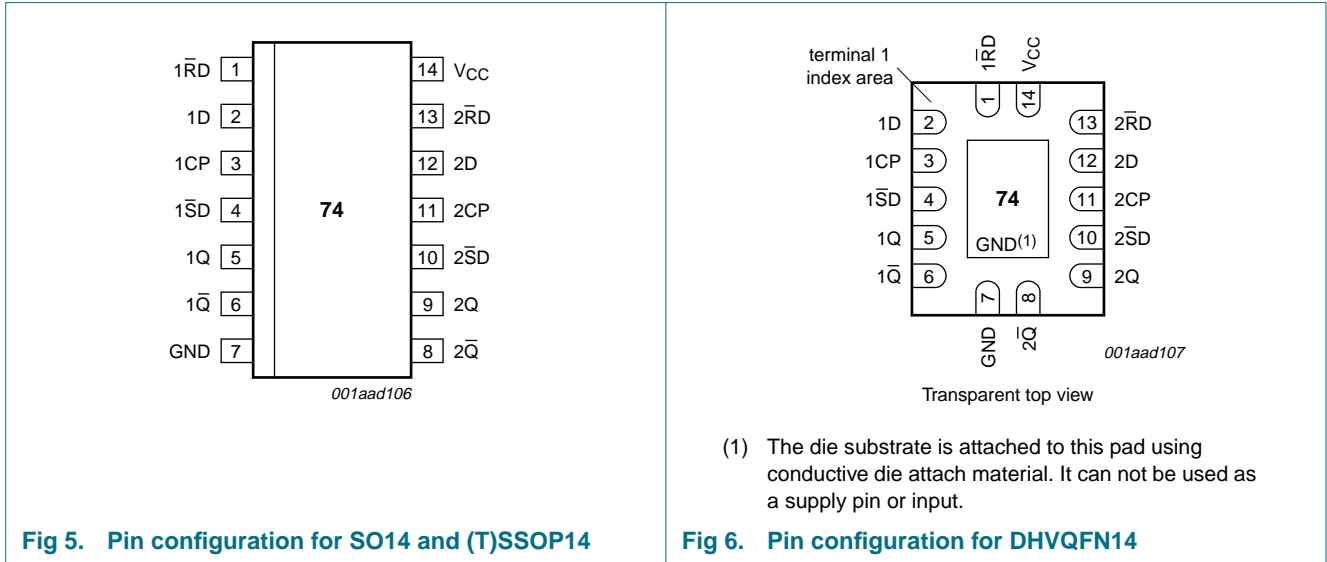


Fig 4. Logic diagram for one flip-flop

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1RD	1	asynchronous reset-direct input (active LOW)
1D	2	data input
1CP	3	clock input (LOW-to-HIGH, edge-triggered)
1SD	4	asynchronous set-direct input (active LOW)
1Q	5	true output
1Q	6	complement output
GND	7	ground (0 V)
2Q	8	complement output
2Q	9	true output
2SD	10	asynchronous set-direct input (active LOW)
2CP	11	clock input (LOW-to-HIGH, edge-triggered)
2D	12	data input
2RD	13	asynchronous reset-direct input (active LOW)
V _{CC}	14	supply voltage

6. Functional description

Table 3. Function table^[1]

Input				Output	
nSD	nRD	nCP	nD	nQ	nQ̄
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H	H

- [1] H = HIGH voltage level
 L = LOW voltage level
 X = don't care

Table 4. Function table^[1]

Input				Output	
nSD	nRD	nCP	nD	nQ _{n+1}	nQ̄ _{n+1}
H	H	↑	L	L	H
H	H	↑	H	H	L

- [1] H = HIGH voltage level
 L = LOW voltage level
 ↑ = LOW-to-HIGH transition
 Q_{n+1} = state after the next LOW-to-HIGH CP transition
 X = don't care

7. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+6.5	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
V _I	input voltage		[1] -0.5	+6.5	V
I _{OK}	output clamping current	V _O > V _{CC} or V _O < 0 V	-	±50	mA
V _O	output voltage		[2] -0.5	V _{CC} + 0.5	V
I _O	output current	V _O = 0 V to V _{CC}	-	±50	mA
I _{CC}	supply current		-	100	mA
I _{GND}	ground current		-100	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C	[3] -	500	mW

- [1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.
 [2] The output voltage ratings may be exceeded if the output current ratings are observed.
 [3] For SO14 packages: above 70 °C the value of P_{tot} derates linearly with 8 mW/K.
 For (T)SSOP14 packages: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.
 For DHVQFN14 packages: above 60 °C the value of P_{tot} derates linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CC}	supply voltage	for maximum speed performance	2.7	-	3.6	V
		for low-voltage applications	1.2	-	3.6	V
V _I	input voltage		0	-	5.5	V
V _O	output voltage		0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 1.2 V to 2.7 V	0	-	20	ns/V
		V _{CC} = 2.7 V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 7. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 1.2 V	V _{CC}	-	-	V _{CC}	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.2 V	-	-	0	-	0	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}	V _{CC} - 0.2	-	-	V _{CC} - 0.3	-	V
		I _O = -100 μA; V _{CC} = 2.7 V to 3.6 V						
		I _O = -12 mA; V _{CC} = 2.7 V	2.2	-	-	2.05	-	V
		I _O = -18 mA; V _{CC} = 3.0 V	2.4	-	-	2.25	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = 100 μA; V _{CC} = 2.7 V to 3.6 V	-	-	0.2	-	0.3	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	-	0.4	-	0.6	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	-	0.55	-	0.8	V
I _I	input leakage current	V _{CC} = 3.6 V; V _I = 5.5 V or GND	-	±0.1	±5	-	±20	μA
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = V _{CC} or GND; I _O = 0 A	-	0.1	10	-	40	μA
ΔI _{CC}	additional supply current	per input pin; V _{CC} = 2.7 V to 3.6 V; V _I = V _{CC} - 0.6 V; I _O = 0 A	-	5	500	-	5000	μA
C _I	input capacitance	V _{CC} = 0 V to 3.6 V; V _I = GND to V _{CC}	-	4.0	-	-	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t _{pd}	propagation delay	nCP to nQ, nQ̄; see Figure 7 ^[2]						
		V _{CC} = 1.2 V	-	15	-	-	-	ns
		V _{CC} = 2.7 V	1.0	2.7	6.0	1.0	7.5	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.5	5.2	1.0	6.5	ns
		nSD to nQ, nQ̄; see Figure 8						
		V _{CC} = 1.2 V	-	15	-	-	-	ns
		V _{CC} = 2.7 V	1.0	3.2	6.4	1.0	8.0	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.5	5.4	1.0	7.0	ns
		nRD to nQ, nQ̄; see Figure 8						
		V _{CC} = 1.2 V	-	15	-	-	-	ns
		V _{CC} = 2.7 V	1.0	3.2	6.4	1.0	8.0	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.5	5.4	1.0	7.0	ns
t _w	pulse width	clock HIGH or LOW; see Figure 7						
		V _{CC} = 2.7 V	3.3	-	-	4.5	-	ns
		V _{CC} = 3.0 V to 3.6 V	3.3	1.3	-	4.5	-	ns
		set or reset LOW; see Figure 8						
		V _{CC} = 2.7 V	3.3	-	-	4.5	-	ns
		V _{CC} = 3.0 V to 3.6 V	3.3	1.7	-	4.5	-	ns
t _{rec}	recovery time	set or reset; see Figure 8						
		V _{CC} = 2.7 V	1.5	-	-	1.0	-	ns
		V _{CC} = 3.0 V to 3.6 V	+1.0	-3.0	-	1.0	-	ns
t _{su}	set-up time	nD to nCP; see Figure 7						
		V _{CC} = 2.7 V	2.2	-	-	2.2	-	ns
		V _{CC} = 3.0 V to 3.6 V	2.0	0.8	-	2.0	-	ns
t _h	hold time	nD to nCP; see Figure 7						
		V _{CC} = 2.7 V	1.0	-	-	1.0	-	ns
		V _{CC} = 3.0 V to 3.6 V	+1.0	-0.2	-	1.0	-	ns
f _{max}	maximum frequency	nCP; see Figure 7						
		V _{CC} = 2.7 V	83	-	-	66	-	MHz
		V _{CC} = 3.0 V to 3.6 V	150	250		120	-	MHz
t _{sk(o)}	output skew time	V _{CC} = 3.0 V to 3.6 V ^[3]	-	-	1.0	-	1.5	ns
C _{PD}	power dissipation capacitance	per flip-flop; V _I = GND to V _{CC} ^[4]						
		V _{CC} = 3.3 V	-	15	-	-	-	pF

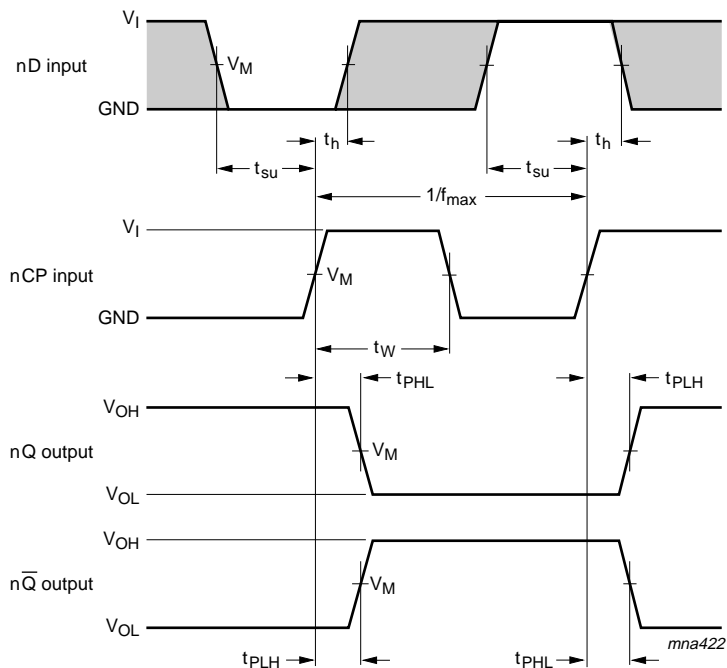
[1] Typical values are measured at T_{amb} = 25 °C. For V_{CC} = 3.0 V to 3.6 V range, typical values are measured at 3.3 V.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

- [4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz; f_o = output frequency in MHz
 C_L = output load capacitance in pF
 V_{CC} = supply voltage in Volts
 N = number of inputs switching
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs

11. AC waveforms



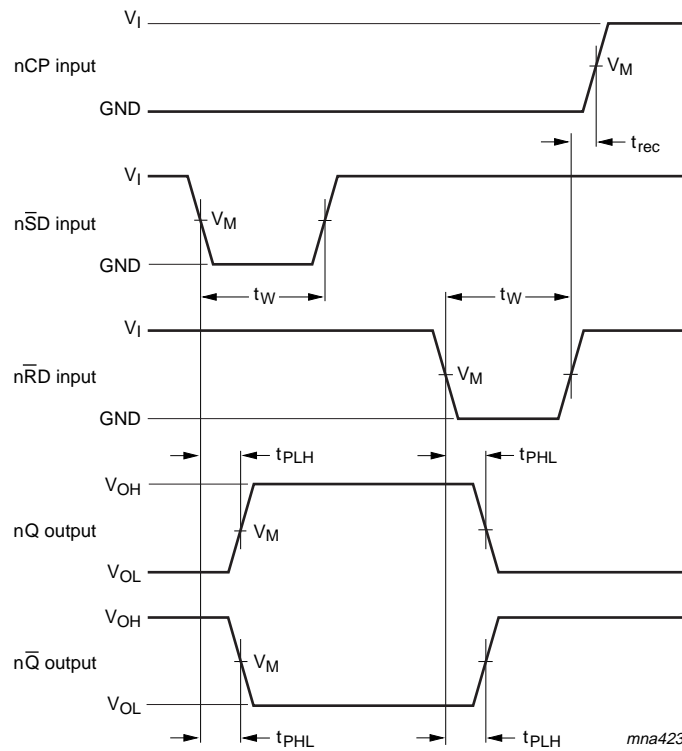
The shaded areas indicate when the input is permitted to change for predictable output performance.

$V_M = 1.5 V$ at $V_{CC} \geq 2.7 V$;

$V_M = 0.5 \times V_{CC}$ at $V_{CC} < 2.7 V$;

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 7. The clock input (nCP) to output (nQ, nQ-bar) propagation delays, the clock pulse width, the nD to nCP set-up, the nCP to nD hold times, and the maximum frequency

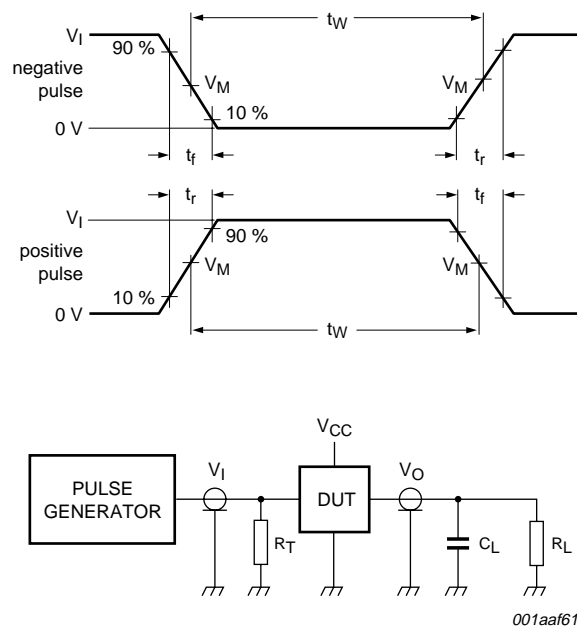


$V_M = 1.5 \text{ V}$ at $V_{CC} \geq 2.7 \text{ V}$;

$V_M = 0.5 \times V_{CC}$ at $V_{CC} < 2.7 \text{ V}$;

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 8. The set ($n\bar{S}D$) and reset ($n\bar{R}D$) input to output (nQ , $n\bar{Q}$) propagation delays, the set and reset pulse widths, and the $n\bar{R}D$ to nCP recovery time



Test data is given in [Table 9](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

Fig 9. Load circuitry for switching times

Table 9. Test data

Supply voltage	Input		Load	
	V_I	t_r, t_f	C_L	R_L
1.2 V	V_{CC}	≤ 2.5 ns	50 pF	500 Ω
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

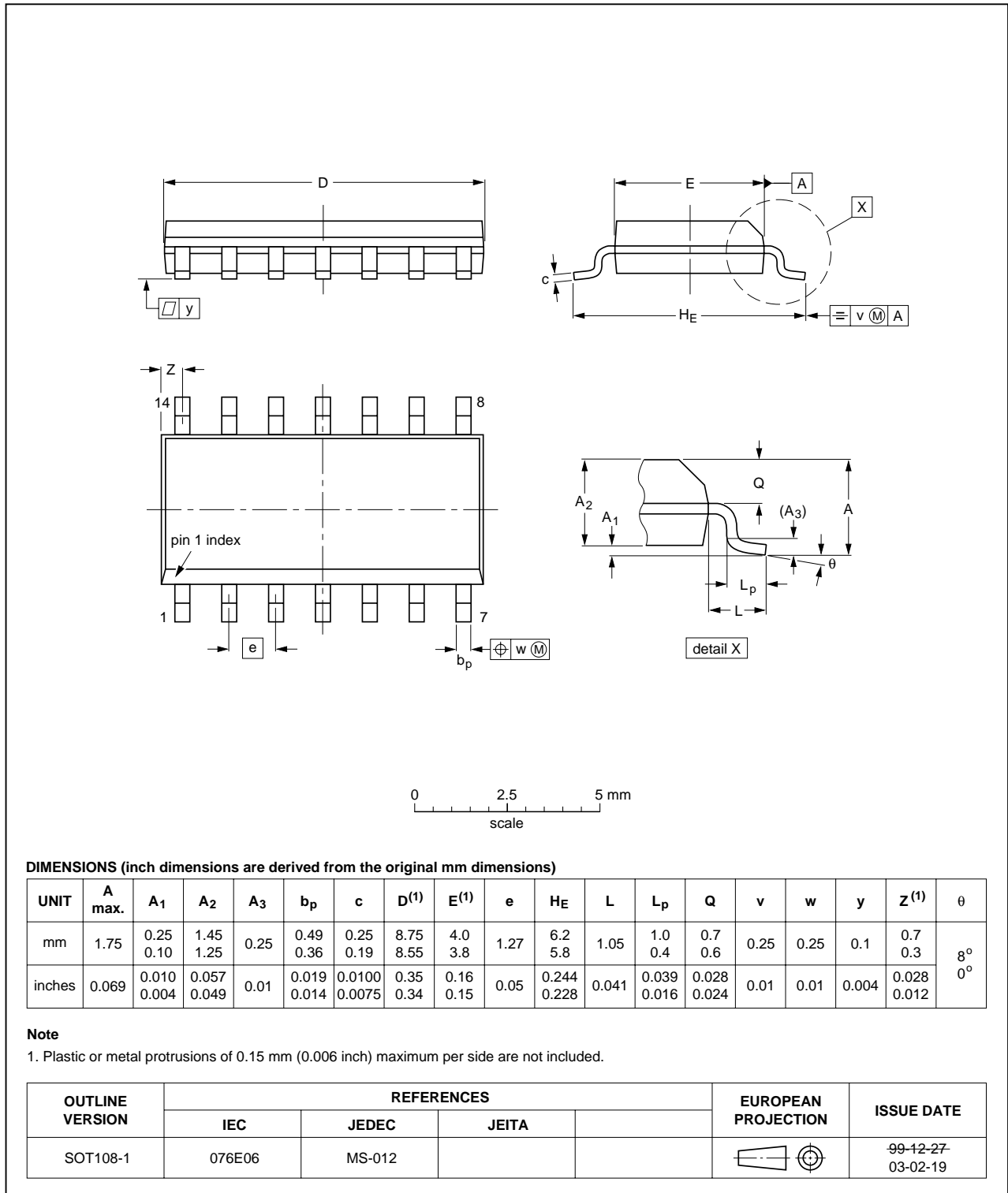


Fig 10. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

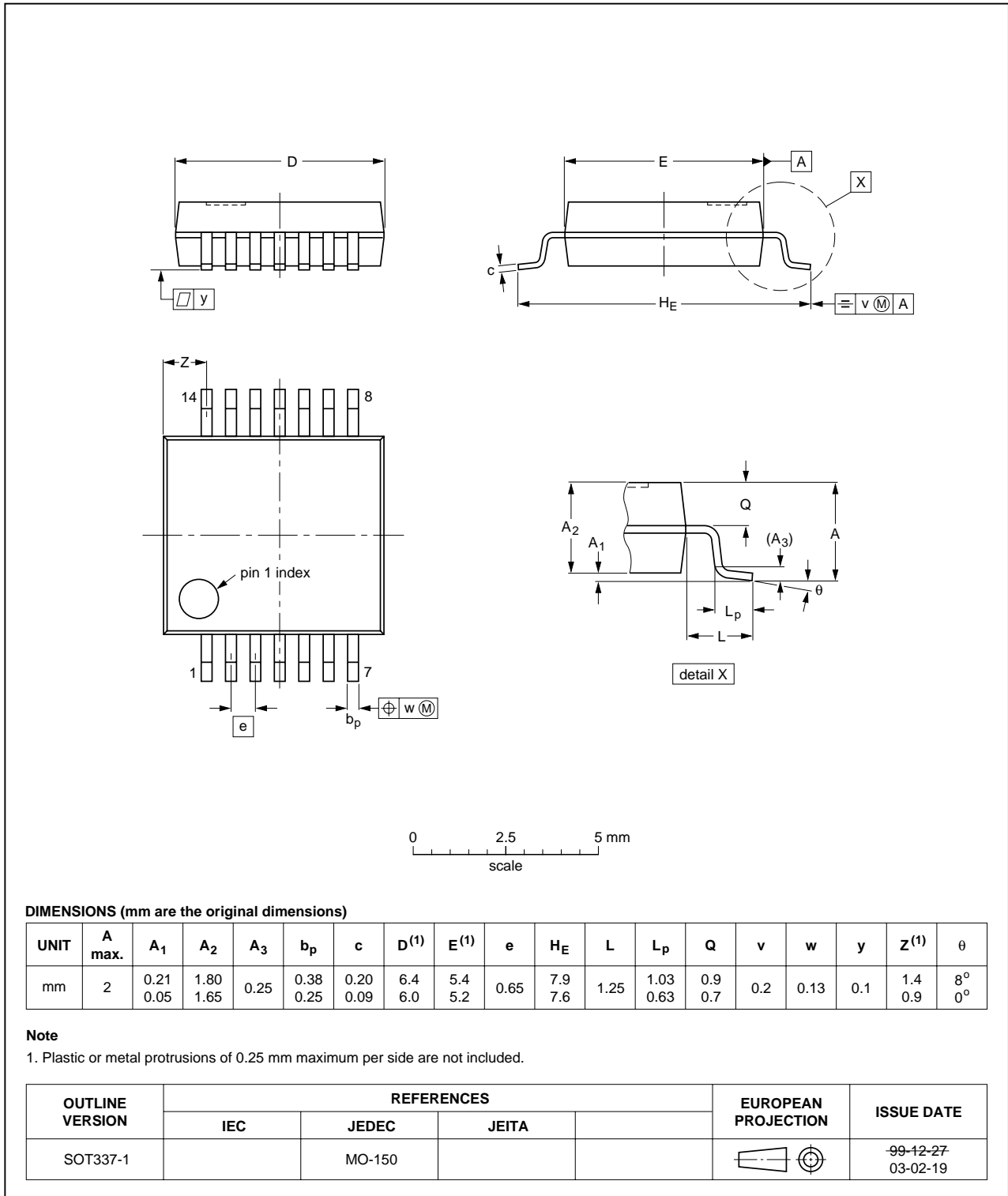


Fig 11. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

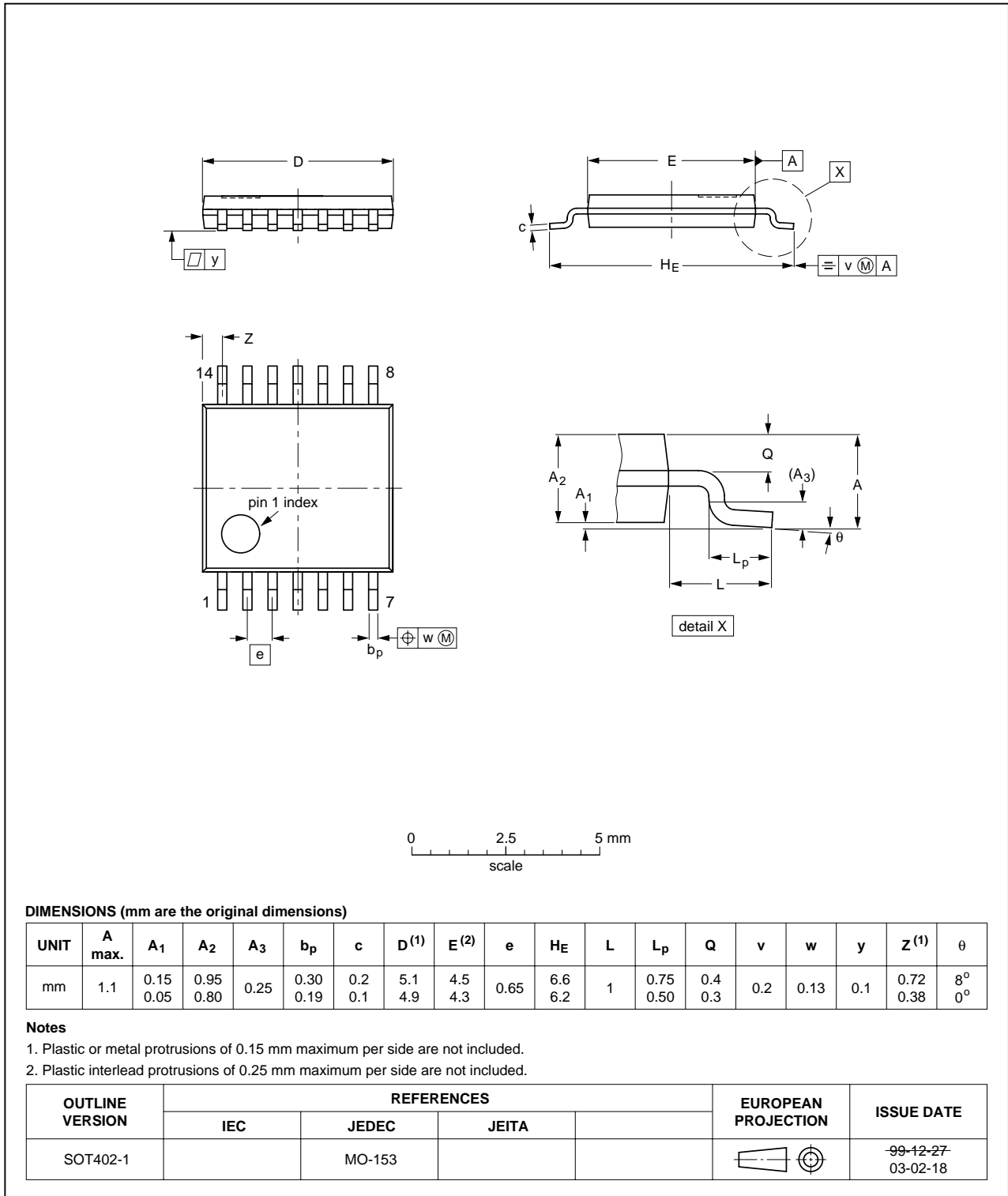


Fig 12. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

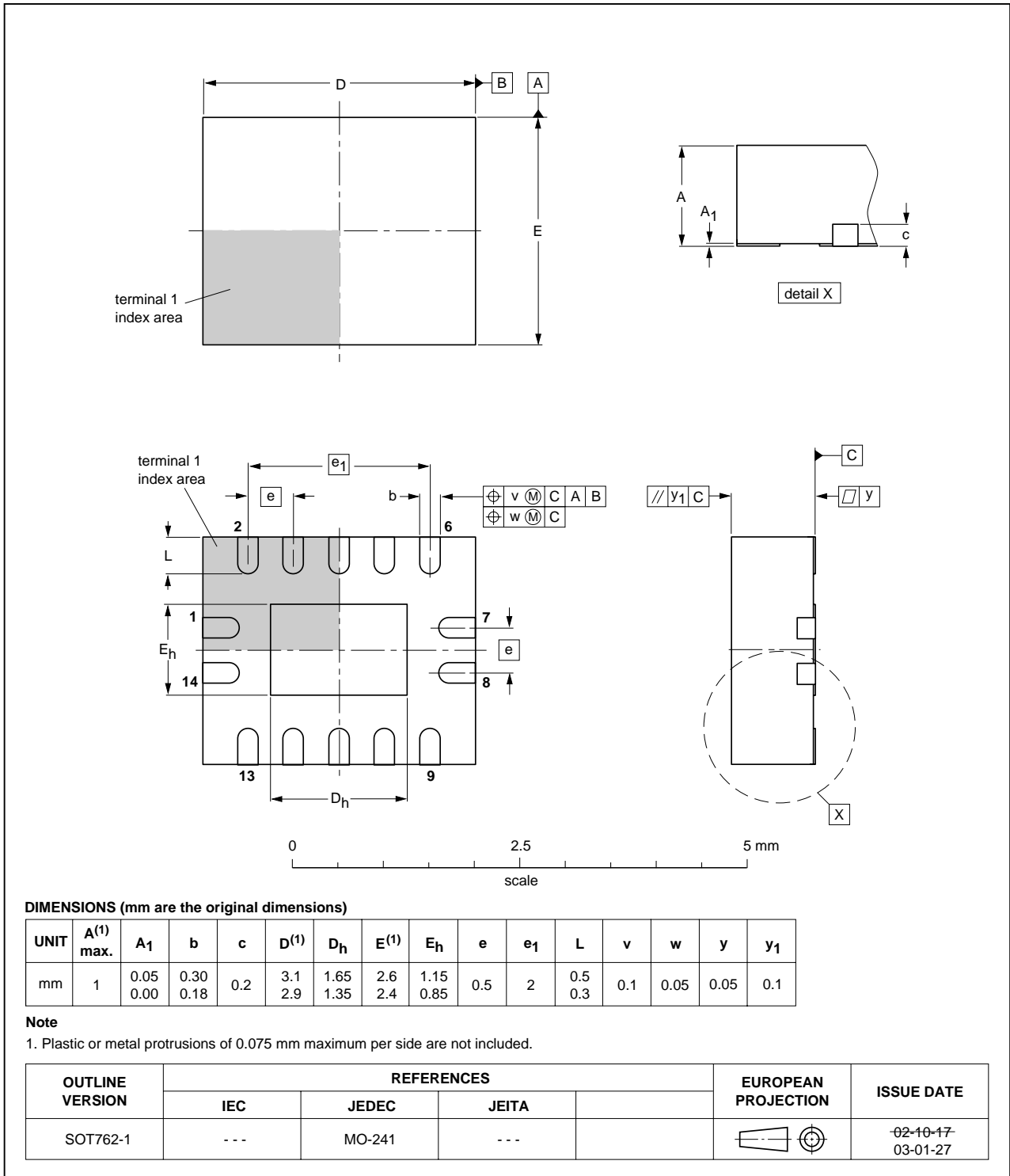


Fig 13. Package outline SOT762-1 (DHVQFN14)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC74A_6	20070604	Product data sheet	-	74LVC74A_5
Modifications:	<ul style="list-style-type: none"> Change of hold time in Table 8 "Dynamic characteristics". Minimum values changed to 1.0 ns. 			
74LVC74A_5	20070525	Product data sheet	-	74LVC74A_4
74LVC74A_4	20030526	Product specification	-	74LVC74A_3
74LVC74A_3	20020618	Product specification	-	74LVC74A_2
74LVC74A_2	19980617	Product specification	-	74LVC74A_1
74LVC74A_1	19980617	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Date of release: 4 June 2007

Document identifier: 74LVC74A_6